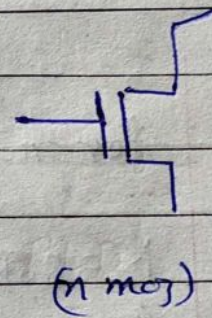
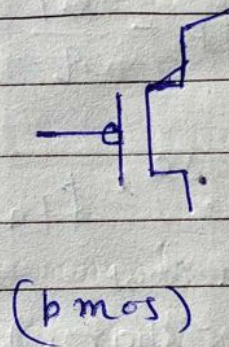
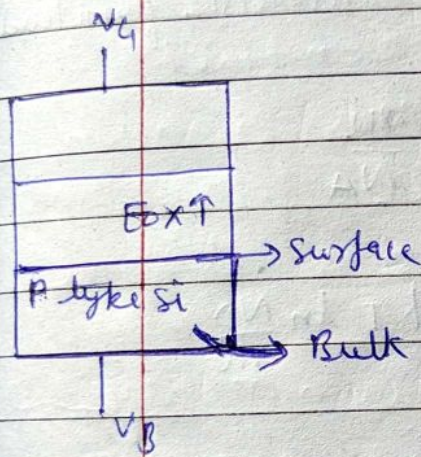
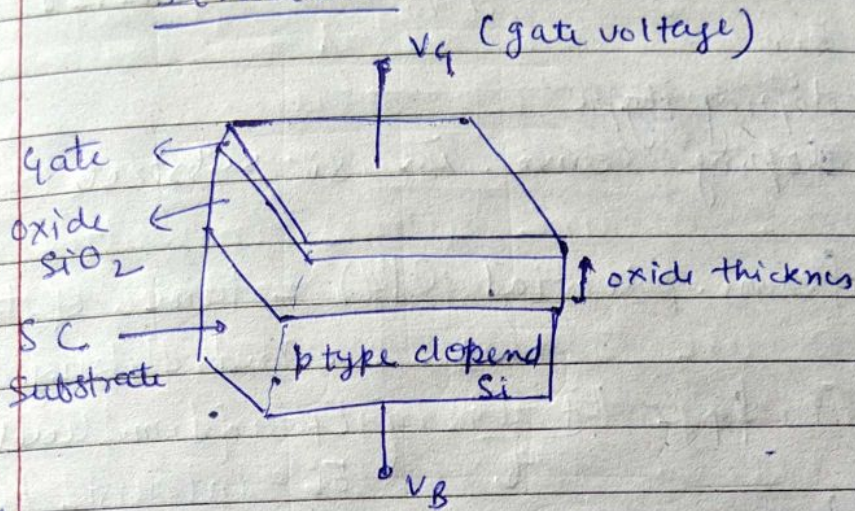
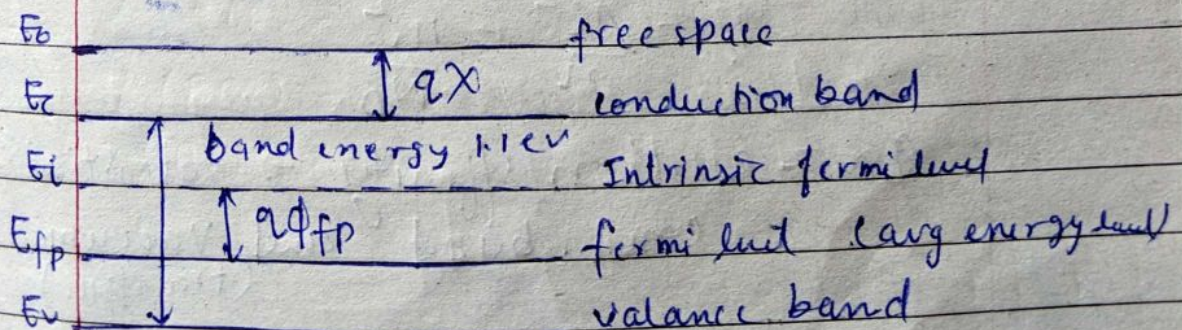


VLSI

The metal oxide semiconductor structure



Energy band diagram of p-type Si substrate



$$E_f = \frac{1}{2} \text{ (intrinsic)}$$

Location of equilib fermi level within band gap is determined by

- (i) doping type
- (ii) doping conc. in si substrate

fermi potential (ϕ_f) = func. of temp and doping

$$\phi_f = \frac{E_f - E_i}{q} \quad \left(\begin{array}{l} E_f = \text{fermi level} \\ E_i = \text{intrinsic fermi level} \end{array} \right)$$

for p-type sc,

$$\phi_{fp} = \frac{KT}{q} \ln \frac{n_i}{N_A}$$

for n-type sc, $\phi_{fn} = \frac{KT}{q} \ln \frac{N_D}{n_i}$

K = Boltzmann const

q = unit (e^- charge)

$$n \cdot p = n_i^2$$

$$n = N_D$$

$$p = N_A$$

$$p = \frac{n_i^2}{n} = \frac{n_i^2}{N_D}$$

$q\chi$ = electron affinity \rightarrow potential b/w cond. band and vacuum level (free space)

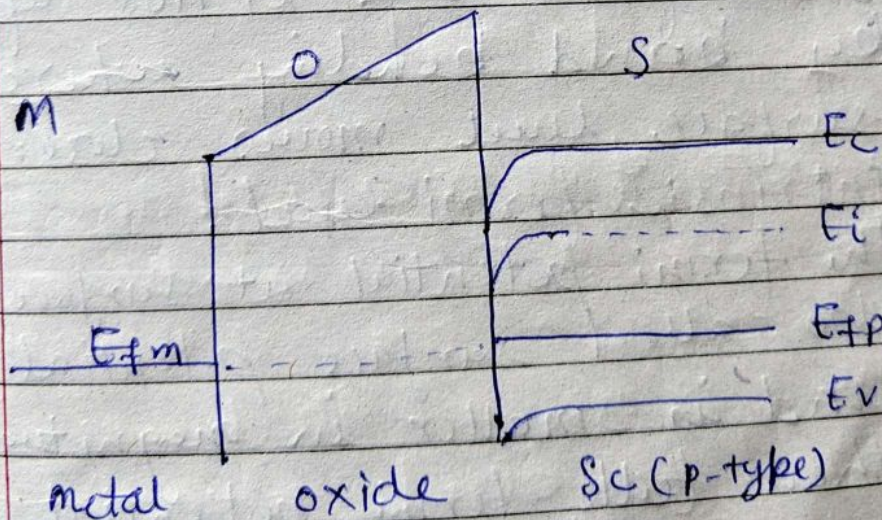
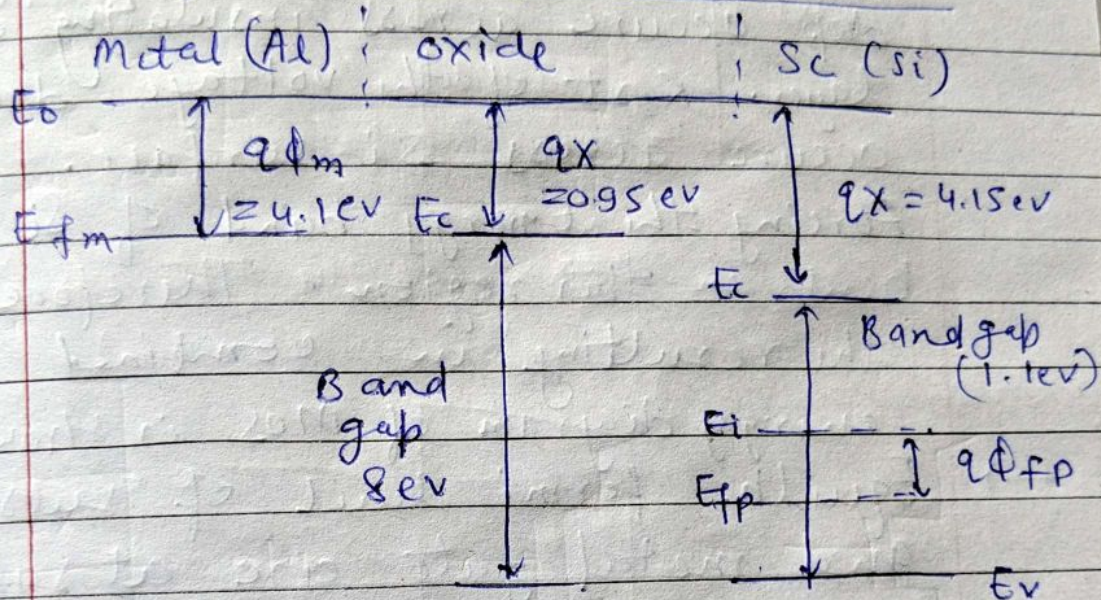
work function ($q\phi_s$) \rightarrow energy required for an e^- to move from fermi level to free space

$$\therefore q\phi_s = q\chi + (E_c - E_f)$$

Band gap E_g of $\text{SiO}_2 = 8.8 \text{ eV}$

$q\chi$ (Al gate) $= 0.95 \text{ eV}$

Energy band diagram of Mos system



Energy band diagram of combined mos system

→ Consider a 3 comp of ideal mos system because of work function difference b/w metal & semiconductor a voltage drop occurs across mos system. Built in voltage drop occurs across insulating oxide layer. Rest of the voltage drop occurs across Si surface.

Forcing the Energy band of Si to bent in this region. Therefore the resulting in combined energy diagram of MOS is shown.

→ Equilib. fermi level of substrate and metal gate are at same potential.

→ Bulk fermi level is not affected by band bending whereas surface level moves closer to intrinsic fermi level.

→ The fermi potential at surface is also called surface potential ϕ_s . And is smaller in magnitude than bulk fermi potential ϕ_f .

$$\phi_s < \phi_f$$

MOS

Ass

(i) Acc

the

(1) A

(2) D

(3) 3

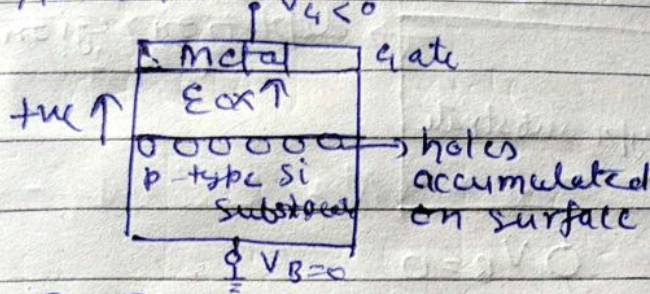
(12)

(1)

MOS system under external bias

Assumption $\rightarrow V_B = 0$
 \rightarrow Gate voltage $\rightarrow V_G \Rightarrow$ controlling parameter

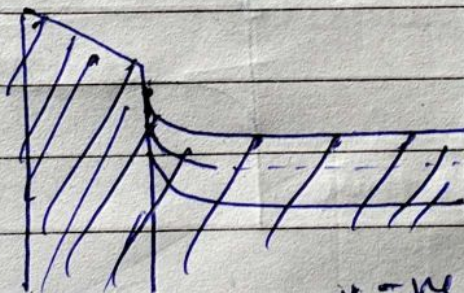
① Accumulation $V_G < 0$



3 Regions:

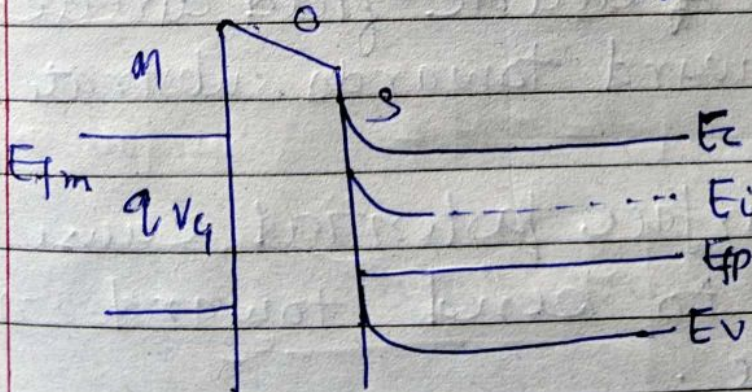
- ① Accumulation region
- ② Depletion region
- ③ Inversion region

②

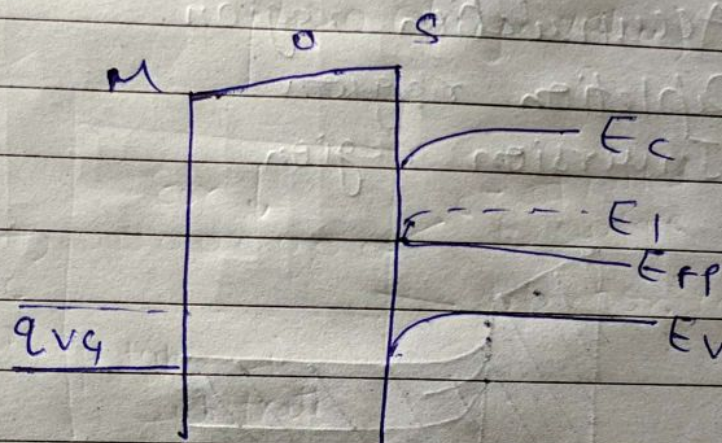
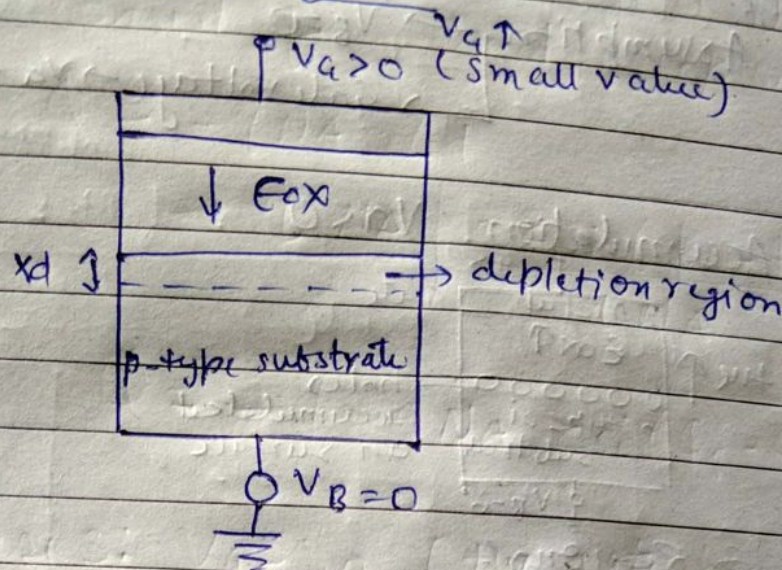


* -ve surface potential cause energy band to

①



② Depletion region



$E_{ox} \Rightarrow$ electric field directed downward towards substrate

the surface potential cause energy band to bend toward near surface.

Find Thickness x_d of depletion region?

Assume mobile hole charges in a thin horizontal layer 11 to surface

$$dQ = -q N_A dx \quad \text{--- (1)}$$

N_A = acceptor ion conc

q = unit (e^-) charge

change in surface potential ($d\phi_s$) \rightarrow reqd. to displace this dQ by distance x_d away from the surface (found by Poisson eqn)

$$q = CV$$

$$\frac{q}{C} = V \quad d\phi_s = -\frac{x dQ}{\epsilon_{si}} = \frac{q N_A x dx}{\epsilon_{si}} \quad \text{--- (2)}$$

$\epsilon_{si} \rightarrow$ dielectric const. of capacitor

Integrating eq (2) along vertical dimension

$$\int_{\phi_f}^{\phi_s} d\phi_s = \int_0^{x_d} \frac{q N_A x}{\epsilon_{si}} dx$$

$$\phi_s - \phi_f = \left| \frac{q N_A x^2}{2 \epsilon_{si}} \right|_0^{x_d}$$

$$= \frac{q N_A x_d^2}{2 \epsilon_{si}}$$

Depth of depletion region

$$x_d = \sqrt{\frac{2 \epsilon_{si} (\phi_s - \phi_f)}{q N_A}} \quad \text{--- (3)}$$

Depletion region charge (Q) \rightarrow consist of fixed acceptor ions

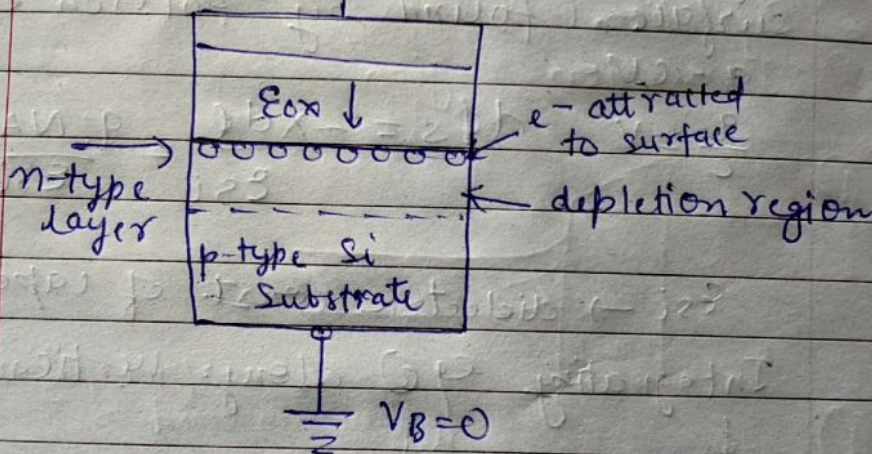
$$Q = -q N_A \cdot X_d$$

$$= -q N_A \sqrt{\frac{2 \epsilon_{Si} (\phi_s - \phi_f)}{q N_A}}$$

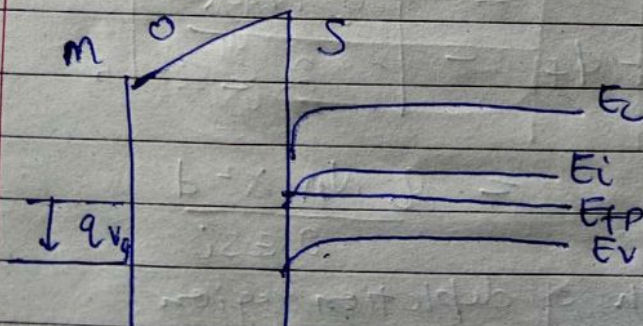
$$Q = -\sqrt{2 q N_A \epsilon_{Si} (\phi_s - \phi_f)} \quad (4)$$

Case 3: $V_a \gg 0$ (the gate bias)

$q V_a \gg 0$ (large value)



$$\phi_s = -\phi_f \quad (\text{Surface inversion})$$



Depletion region depth $\phi_s = \phi_f$

$$X_{dm} = \sqrt{\frac{2 \epsilon_{Si} / 2 \phi_f}{q N_A}}$$

\rightarrow Incr surf of en of E_i on s
 \rightarrow Surf this larg N-t by bias the c inve but

→ Increase the gate bias increases surface potential downward bending of energy band increases.
 E_i becomes smaller than E_{fp} on surface.

→ Surface becomes n-type within this layer electron density becomes larger than hole density.

→ N-type region created near surface by the gate surface by the gate bias called inversion layer. And the condition is called as surface inversion ϕ_s , has same magnitude but reverse polarity as ϕ_f
 i.e $\phi_s = -\phi_f$